NUS National University of Singapore **CIBA** Faculty of Science, Dept of Physic ,Centre of Ion Beam Applications	Procedure No:	CIBA/SOP/Exp/004
Title: **Parallel UV Lithography**	Rev No: Issue Date:	0001 14 Nov 2008
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1 Objective:

This Standard Operation Procedure states the procedure of Parallel UV lithography.

2 Responsibilities:

2.1 Director / HOD / PI

The Director/HOD/PI has overall responsibility for ensuring a system is established for Parallel UV lithography.

2.2 Designated Person

There shall be a designated person to oversee the correct operation of Parallel UV lithography.

a. He/she will report to the Director/HOD/PI unsafe practices by direct Parallel UV lithography users.

2.3 Staff / Research personnel

a. Parallel UV lithography users shall attend appropriate training on the safe use of the machine.

b. Users shall report any injuries, defects or breakdowns to their supervisor.

3 Procedures:

1. Wear a clean pair of gloves, UV goggles and lab coat.
2. Switch on the vacuum pump.
3. Open compressed air valve (clean room only).
4. Position the desired UV light source in the exposure position (clean room only).
5. Switch on power supply.
6. After 3 min press start/stop.
7. Place resist coated wafer on vacuum chuck. Place the mask in mask holder.
8. If needed align wafer with respect to mask using camera system.
9. Move sample stack under the UV light source.
10. Open shutter to expose your sample.
11. Close shutter, unload the sample (and mask).
12. Switch off vacuum and close compressed air valve.
13. Switch of UV lamp, press start/stop.
14. After 15 min switch off the power supply and close exhaust valve.